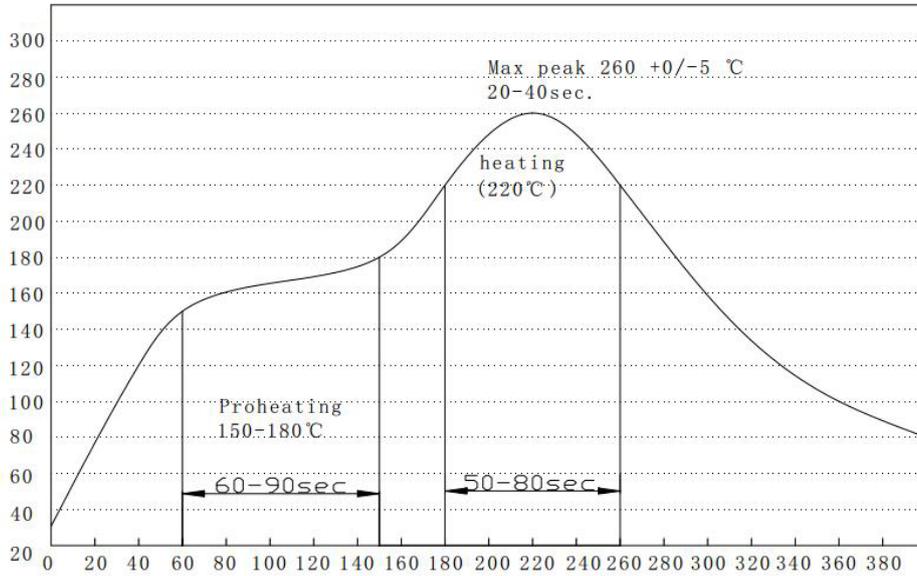


Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	